

In the Specification:

Please amend paragraph [0028] as follows:

[0028] In addition to the rigid individual layer 4 which is copper-clad on one side in the embodiment shown, both the known circuit board 1 and also the circuit board 1 as claimed in accordance with the invention have an adhesive medium 7 and a copper foil 8. The adhesive medium 7 which is generally formed from a prepreg, in the flexible area 3 has a recess so that the piece 5 does not become cemented to the adhesive medium 7.

Please amend paragraph [0031] as follows:

[0031] In one preferred embodiment of the circuit board 1 according to the invention and of the process of the invention, for producing a rigid-flexible circuit board 1, the insulating layer 11 is applied to the copper foil 8 before the circuit board 1 is cemented and pressed. To do this, for example, a flexible plastic resist, especially a flexible solder resist, can be sprayed or imprinted onto the corresponding site on the copper foil 8. Using methods such as spraying, printing or rolling, the insulating layer 11 can be applied to the desired locations of a copper foil 8 very easily, promptly and accurately in terms of position. In doing so, at the same time, a host of insulating layers 11 can be applied to a copper foil 8 of a corresponding size so that in one process step a copper foil 8 [[9]] can be prepared for several circuit boards 1.